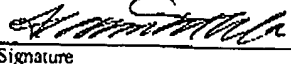


This amendment clarifies Claim 1; Claim 1 as earlier pending in its second to last line said "second electrical terminal" when it should have said "first electrical terminal." Also, this amendment substitutes "back" for "first" and "front" for "second" when referring to the die sides, for greater clarity. See specification page 2, line 27 and page 3, line 10 for support.

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I hereby certify that this paper is being facsimile transmitted to the U.S. Patent and Trademark Office on the date shown below.	
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Respectfully submitted,



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APPENDIX A - Changes to the Claims

1. (Four times amended) A semiconductor package comprising:

a semiconductor die having [a first and second] front and back sides, a first electrical terminal being located on the [first] back side, at least a second electrical terminal being located on the [second] front side; and

a leadframe in electrical contact with the first terminal, the leadframe being formed in the shape of a cup, the die being located in the cup, at least one lead of the leadframe having a portion that extends laterally to be coplanar with the [second] front side of the die along a substantial portion of its length, and the at least one lead being in electrical contact with the [second] first electrical terminal, the [first] back side of the die facing in a direction toward the inside of the cup.

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